

AMENDMENTS

In The Claims

1. (original) A method of spiking a mixed acid liquid in a reactor by using a computer to control a concentration of the mixed acid liquid, the concentration of the mixed acid liquid being controlled at a target level under a based-on-charge mode, a based-on-time mode, or a based-on-time-and-charge mode,  
the based-on-charge mode control comprising:

providing a charge list including a plurality of lot numbers of product and a plurality of spiking amounts of a first acid liquid corresponding lot numbers of product;  
and

introducing the spiking amounts of the first acid into the reactor in an order corresponding to the lot numbers of product;  
the based-on-time mode control comprising:

providing a timing list including a plurality of timing points and a plurality of spiking amounts of a second acid liquid corresponding to the timing points;  
and

introducing the spiking amounts of the second acid liquid into the reactor at the corresponding timing points;

and the based-on-time-and-charge mode control comprising:

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**providing a charge/timing list including spiking amounts and spike timing points; and**

**introducing the spiking amounts of the first acid into the reactor based on the lot numbers of product and the spike timing points.**

**2. (original) The method of claim 1, wherein when a wafer is being etched in the reactor, the acid liquid is not introduced into the reactor.**

**3-7. (Canceled)**

**8. (original) A method of spiking a mixed acid liquid in a reactor by using a computer to control a concentration of the mixed acid liquid, the concentration of the mixed acid liquid being controlled at a target level under a based-on-time-and-charge mode,**

**wherein the based-on-time-and-charge mode control comprises:**

**providing a charge/timing list including spiking amounts and spike timing points; and**

**introducing the spiking amounts of the first acid into the reactor based on lot numbers of product and the spike timing points.**

**9. (original) The method of claim 8, wherein when a wafer is being etched in the reactor, the acid liquid is not introduced into the reactor.**